

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
16 June 2005 (16.06.2005)

PCT

(10) International Publication Number
WO 2005/055300 A1

(51) International Patent Classification⁷: **H01L 21/301**,
21/86, 33/00

(21) International Application Number:
PCT/JP2004/018325

(22) International Filing Date: 2 December 2004 (02.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-407550 5 December 2003 (05.12.2003) JP
60/534,193 2 January 2004 (02.01.2004) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

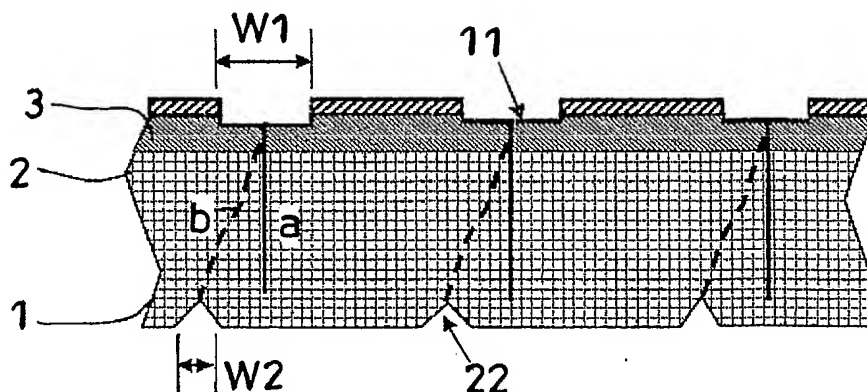
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD FOR PRODUCTION OF SEMICONDUCTOR CHIP AND SEMICONDUCTOR CHIP



(57) Abstract: A method for the production of gallium nitride compound semiconductor chips from a wafer having gallium nitride compound semiconductor layers (2, 3) laminated on the principal surface of a substrate (1) comprises a step of forming first grooves (11) linearly in a desired chip shape by etching on the gallium nitride compound semiconductor layers (2, 3) sides of the wafer, a step of forming second grooves (22) having a nearly equal or smaller line width (W2) than a line width (W1) of the first grooves on the substrate (1) side of the wafer at positions not conforming to the central lines of the first grooves, and a step of dividing the wafer along the first and second grooves. It consequently allows the wafer to be accurately cut in an extremely high yield, with the result that the number of chips taken out of one wafer will be increased and the productivity will be enhanced.

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